

UP 4000 EDGE

Edge System
UP-EDGE-APL03

User's Manual 1st Ed

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Packing List

Before setting up your product, please make sure the following items have been shipped:

Item	Quantity
● UP-EDGE-APL03 (UP 4000 EDGE) with heatsink	1

If any of these items are missing or damaged, please contact your distributor or sales representative immediately.

About this Document

This User's Manual contains all the essential information, such as detailed descriptions and explanations on the product's hardware and software features (if any), its specifications, dimensions, jumper/connector settings/definitions, and driver installation instructions (if any), to facilitate users in setting up their product.

Users may refer to the product page at AAEON.com for the latest version of this document.

Safety Precautions

Please read the following safety instructions carefully. It is advised that you keep this manual for future references

1. All cautions and warnings on the device should be noted.
2. Make sure the power source matches the power rating of the device.
3. Position the power cord so that people cannot step on it. Do not place anything over the power cord.
4. Always completely disconnect the power before working on the system's hardware.
5. No connections should be made when the system is powered as a sudden rush of power may damage sensitive electronic components.
6. If the device is not to be used for a long time, disconnect it from the power supply to avoid damage by transient over-voltage.
7. Always disconnect this device from any AC supply before cleaning.
8. While cleaning, use a damp cloth instead of liquid or spray detergents.
9. Make sure the device is installed near a power outlet and is easily accessible.
10. Keep this device away from humidity.
11. Place the device on a solid surface during installation to prevent falls
12. Do not cover the openings on the device to ensure optimal heat dissipation.
13. Watch out for high temperatures when the system is running.
14. Do not touch the heat sink or heat spreader when the system is running
15. Never pour any liquid into the openings. This could cause fire or electric shock.
16. As most electronic components are sensitive to static electrical charge, be sure to ground yourself to prevent static charge when installing the internal components. Use a grounding wrist strap and contain all electronic components in any static-shielded containers.

17. If any of the following situations arises, please the contact our service personnel:
 - i. Damaged power cord or plug
 - ii. Liquid intrusion to the device
 - iii. Exposure to moisture
 - iv. Device is not working as expected or in a manner as described in this manual
 - v. The device is dropped or damaged
 - vi. Any obvious signs of damage displayed on the device
18. **DO NOT LEAVE THIS DEVICE IN AN UNCONTROLLED ENVIRONMENT WITH TEMPERATURES BEYOND THE DEVICE'S PERMITTED STORAGE TEMPERATURES (SEE CHAPTER 1) TO PREVENT DAMAGE.**

FCC Statement

Warning!



This device complies with Part 15 FCC Rules. Operation is subject to the following two conditions: (1) this device may not cause harmful interference, and (2) this device must accept any interference received including interference that may cause undesired operation.

Caution:

There is a danger of explosion if the battery is incorrectly replaced. Replace only with the same or equivalent type recommended by the manufacturer. Dispose of used batteries according to the manufacturer's instructions and your local government's recycling or disposal directives.

Attention:

Il y a un risque d'explosion si la batterie est remplacée de façon incorrecte. Ne la remplacer qu'avec le même modèle ou équivalent recommandé par le constructeur. Recycler les batteries usées en accord avec les instructions du fabricant et les directives gouvernementales de recyclage.

产品中有毒有害物质或元素名称及含量

AAEON System

QO4-381 Rev.A0

部件名称	有毒有害物质或元素					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
印刷电路板 及其电子组件	×	○	○	○	○	○
外部信号 连接器及线材	×	○	○	○	○	○
外壳	○	○	○	○	○	○
中央处理器 与内存	×	○	○	○	○	○
硬盘	×	○	○	○	○	○
液晶模块	×	○	○	○	○	○
光驱	×	○	○	○	○	○
触控模块	×	○	○	○	○	○
电源	×	○	○	○	○	○
电池	×	○	○	○	○	○

本表格依据 SJ/T 11364 的规定编制。

○：表示该有毒有害物质在该部件所有均质材料中的含量均在 GB/T 26572 标准规定的限量要求以下。

×：表示该有害物质的某一均质材料超出了 GB/T 26572 的限量要求，然而该部件仍符合欧盟指令 2011/65/EU 的规范。

备注：

- 一、此产品所标示之环保使用期限，系指在一般正常使用状况下。
- 二、上述部件物质中央处理器、内存、硬盘、光驱、电源为选购品。
- 三、上述部件物质液晶模块、触控模块仅一体机产品适用。

China RoHS Requirement (EN)

Hazardous and Toxic Materials List

AAEON System

QQ4-381 Rev.A0

Component Name	Hazardous or Toxic Materials or Elements					
	Lead (Pb)	Mercury (Hg)	Cadmium (Cd)	Hexavalent Chromium (Cr(VI))	Polybrominated biphenyls (PBBS)	Polybrominated ethers (PBDES)
PCB and Components	X	O	O	O	O	O
Wires & Connectors for Ext.Connections	X	O	O	O	O	O
Chassis	O	O	O	O	O	O
CPU & RAM	X	O	O	O	O	O
HDD Drive	X	O	O	O	O	O
LCD Module	X	O	O	O	O	O
Optical Drive	X	O	O	O	O	O
Touch Control Module	X	O	O	O	O	O
PSU	X	O	O	O	O	O
Battery	X	O	O	O	O	O

This form is prepared in compliance with the provisions of SJ/T 11364.
 O: The level of toxic or hazardous materials present in this component and its parts is below the limit specified by GB/T 26572.
 X: The level of toxic or hazardous materials present in the component exceed the limits specified by GB/T 26572, but is still in compliance with EU Directive 2011/65/EU (RoHS 2).

Notes:

1. The Environment Friendly Use Period indicated by labelling on this product is applicable only to use under normal conditions.
2. Individual components including the CPU, RAM/memory, HDD, optical drive, and PSU are optional.
3. LCD Module and Touch Control Module only applies to certain products which feature these components.

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Chapter 1

Product Specifications

1.1 Specifications

System

CPU	Intel® Pentium® N4200/ Celeron® N3350/ Atom E3950™
Memory	Onboard LPDDR4 Memory up to 8GB
Graphics	Intel® Gen 9 HD, supporting 4K Codec Decode and Encode for HEVC4, H.264, VP8
Storage	Onboard eMMC Storage, up to 64GB
Ethernet	Gb Ethernet (full speed) RJ-45 x 1
WIFI/BT	—
Expansion Slot	—
Security	TPM 2.0
OS Support	Microsoft Windows 10 (full), Windows IOT Core Yocto project 3.1 Kernel 5.4 Ubuntu 18.04

I/O Placements

USB	USB 3.2 Gen 1 (Type A) x 3 USB 3.0 OTG via USB type C x 1
Display Port	HDMI 1.4b x 1 DP via USB Type C
Ethernet	RJ45 x 1
COM	—
Audio	Line out x 1 Mic in x 1
GPIO	—

Power Supply

Power Requirement	12V DC-in @ 5A
Power Supply Type	DC Jack, 5.5-2.1mm/Phoenix Colay
Power Consumption (Typical)	12V @ 1.25A (15W)

Mechanical

Mounting	VESA Mounting
Dimensions (W x H x D)	3.62" x 2.52" x 1.78" (92mm x 64mm x 45.2mm)
Net Weight	0.64 lbs. (0.29kg)
Gross Weight	1.21 lbs. (0.54kg)

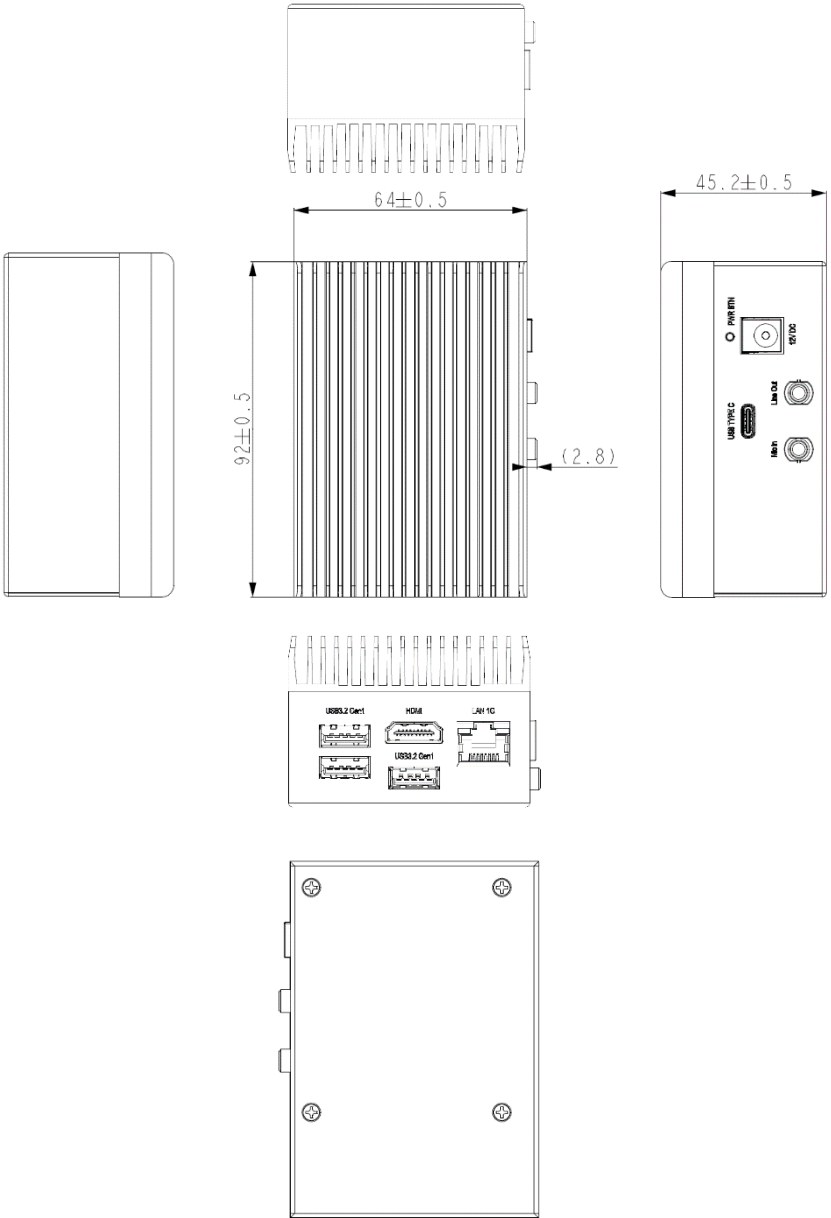
Environmental

Operating Temperature	32°F ~ 140°F (0°C ~ 60°C) with air flow 0.5m/s
Operating Humidity	10% ~ 80% relative humidity, non-condensing
Storage Temperature	-4°F ~ 158°F (-20°C ~ 70°C)
MTBF (Hours)	538,629 @ 30°C
Certification	CE/FCC Class A, RoHS Compliant, REACH

Chapter 2

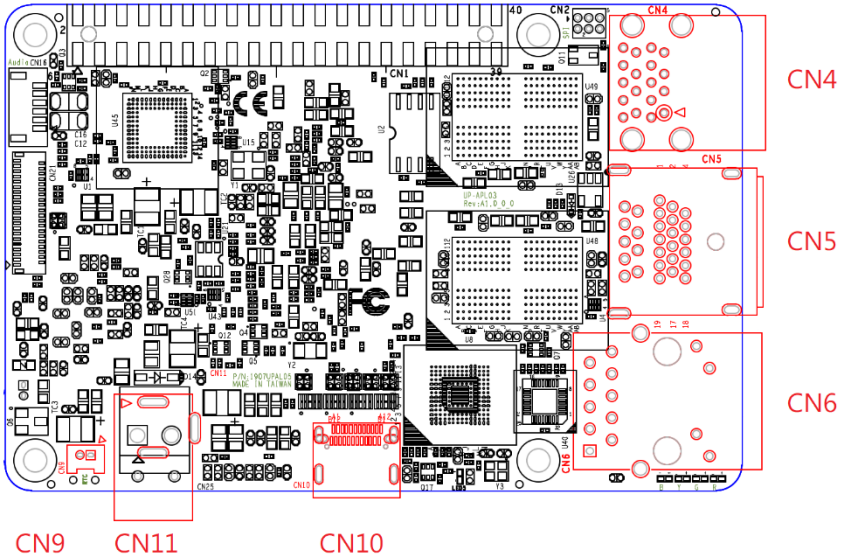
Hardware Information

2.1 Dimensions



2.2 Jumpers and Connectors

Top:



CN9

CN11

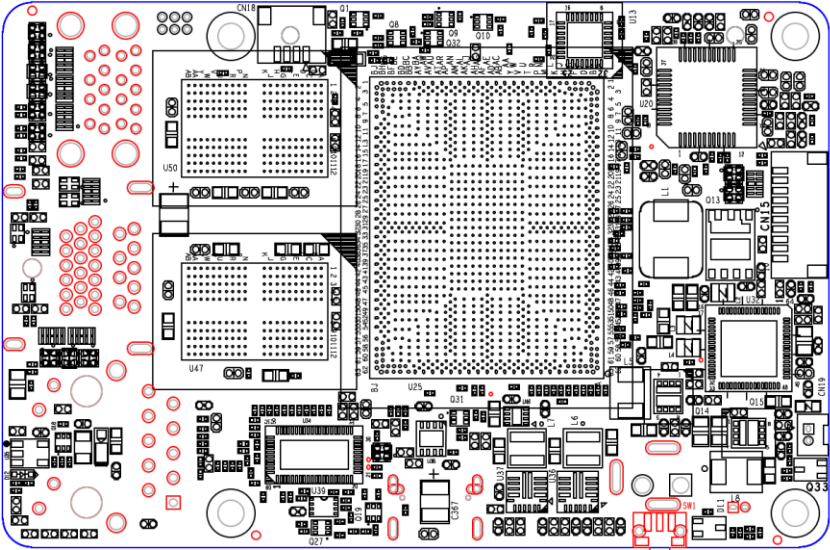
CN10

CN4

CN5

CN6

Bottom:



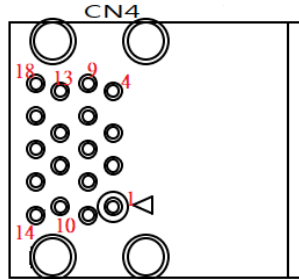
SW1

2.3 List of Connectors

Please refer to the table below for all of the board's connectors that you can configure for your application

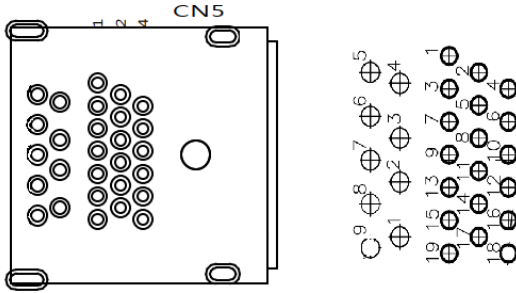
Label	Function
CN4	Dual USB 3.0
CN5	USB3.0 + HDMI
CN6	RJ45
CN9	RTC Conn
CN10	Type-C 3.0
CN11	DC Jack
SW1	Power Button

2.3.1 Dual USB 3.0 (CN4)



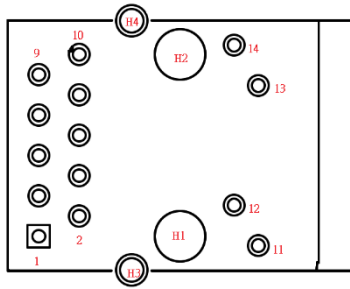
Pin	Signal	Pin	Signal
1	5V@0.9A for USB 3.0	2	USB2.0_DN0
3	USB2.0_DP0	4	GND
5	USB3.0_RXN_P0	6	USB3.0_RXP_P0
7	GND	8	USB3.0_TXN_P0
9	USB3.0_TXP_P0	10	5V@0.9A for USB 3.0
11	USB2.0_DN1	12	USB2.0_DP1
13	GND	14	USB3.0_RXN_P1
15	USB3.0_RXP_P1	16	GND
17	USB3.0_TXN_P1	18	USB3.0_TXP_P1
H1	GND	H2	GND
H3	GND	H4	GND

2.3.2 USB3.0 + HDMI (CN5)



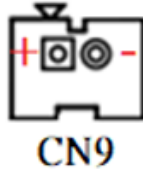
Pin	Signal	Pin	Signal
A1	HDMI_TMDS_TXP2	A2	GND
A3	HDMI_TMDS_TXN2	A4	HDMI_TMDS_TXP1
A5	GND	A6	HDMI_TMDS_TXN1
A7	HDMI_TMDS_TXP0	A8	GND
A9	HDMI_TMDS_TXN0	A10	HDMI_TMDS_Clock_P
A11	GND	A12	HDMI_TMDS_Clock_N
A13	NC	A14	NC
A15	HDMI_DDC_Clock	A16	HDMI_DDC_Data
A17	GND	A18	5V@1A for HDMI
A19	HDMI Hot Plug detect pin	-	-
H1	NC	H2	GND
H3	GND	H4	GND
H5	GND	-	-
B1	5V@0.9A for USB 3.0	B2	USB2.0_DN_P1
B3	USB2.0_DP_P1	B4	GND
B5	USB3.0_RxN_P1	B6	USB3.0_RxP_P1
B7	GND	B8	USB3.0_TxN_P1
B9	USB3.0_TxP_P1	-	-

2.3.3 RJ45 (CN6)



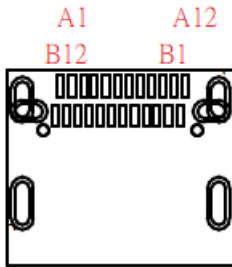
Pin	Signal	Pin	Signal
1	LAN1_MDI0+(TXD+)	2	LAN1_MDI0-(TXD-)
3	LAN1_MDI1+(RXD+)	4	LAN1_MDI1-(RXD-)
5	CT_GND	6	CT_GND
7	LAN1_MDI2+	8	LAN1_MDI2-
9	LAN1_MDI3+	10	LAN1_MDI3-
11	LAN Link LED 1000#	12	LAN Link LED 100#
13	LAN Active LED_N	14	LAN Active LED_P
H1	NC	H2	NC
H3	Chassis_GND	H4	Chassis_GND

2.3.4 RTC Connector (CN9)



Pin	Signal	Pin	Signal
1	3.3V for RTC	2	GND

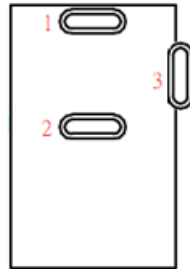
2.3.5 USB Type-C 3.0 (with Alt Mode) (CN10)



Pin	Signal	Pin	Signal
A1	GND	A2	USB3.0_ Type-C_TxP_P1
A3	USB3.0_ Type-C_TxN_P1	A4	5V@3A for USB Type-C
A5	USB Type-C CC pin1	A6	USB2.0_ Type-C_DP_P1
A7	USB2.0_ Type-C_DN_P1	A8	USB Type-C SBU1
A9	5V@3A for USB Type-C	A10	USB3.0_ Type-C_RxP_P2
A11	USB3.0_ Type-C_RxN_P2	A12	GND
B1	GND	B2	USB3.0_ Type-C_TxP_P2

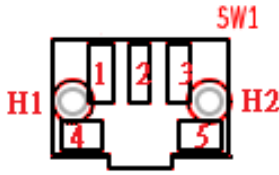
Pin	Signal	Pin	Signal
B3	USB3.0_Type-C_TxN_P2	B4	5V@3A for USB Type-C
B5	USB Type-C CC pin2	B6	USB2.0_Type-C_DP_P1
B7	USB2.0_Type-C_DN_P1	B8	USB Type-C SBU2
B9	5V@3A for USB Type-C	B10	USB3.0_Type-C_RxP_P1
B11	USB3.0_Type-C_RxN_P1	B12	GND
H1	NC	H2	NC
H3	GND	H4	GND
H5	GND	H6	GND
H7	GND	H8	GND

2.3.6 DC Jack (5.5-2.1mm) (CN11)



Pin	Signal	Pin	Signal
1	12V@7A Input	2	GND
3	GND	-	-

2.3.7 Power Button (SW1)



Pin	Signal	Pin	Signal
1	GND	2	Power Button#
3	GND	4	GND
5	GND	-	-
H1	GND	H2	GND

2.4 Hardware Installation

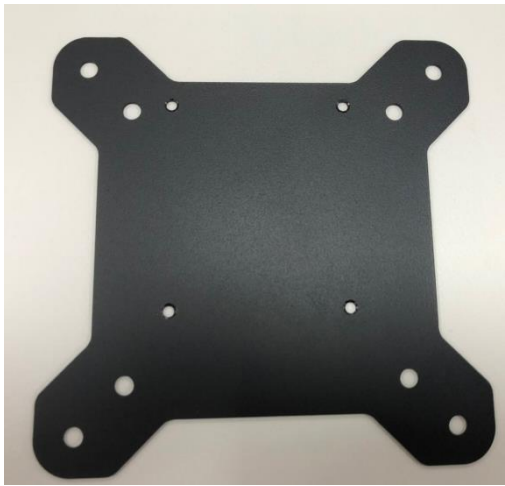
2.4.1 VESA Mount Installation

For this process you will need a Phillips head screwdriver.

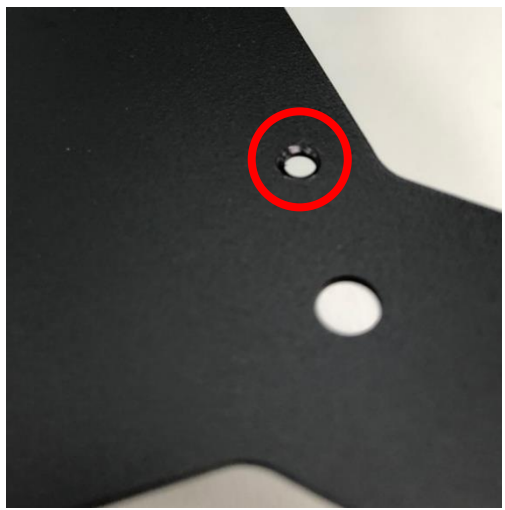
Step 1: Remove screws on the bottom plate.



Step 2: Pick up VESA Bracket.

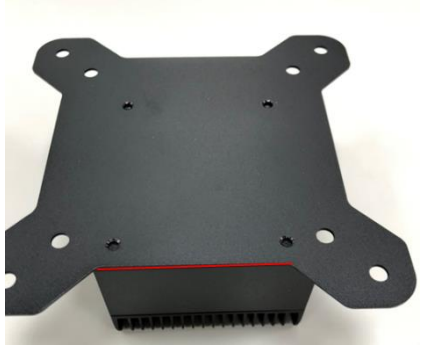


Step 3: Please make sure to counterbore up and align VESA Bracket with the edge of the UP 4000 System in the correct position.



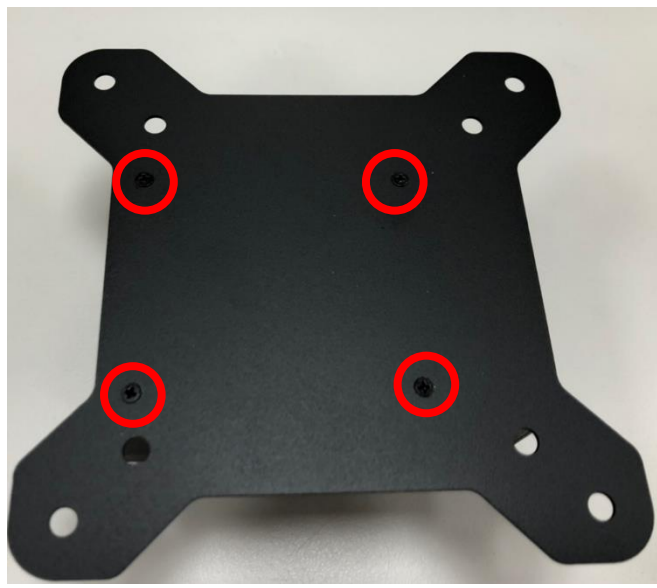


Front View



Back View

Step 4: Use 4 screws (refer to step 1) to lock VESA Bracket.



Chapter 3

Drivers Installation

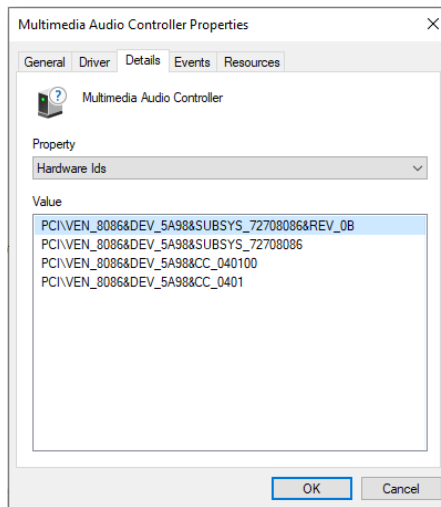
3.1 Driver Download and Installation

Please access <https://www.up-community.org> and go to the Downloads section > UP 4000 EDGE to find the relevant drivers.

3.2 Unknown Device Troubleshooting

After installing the drivers on Windows 10, you may see five unknown devices in the device manager. Follow the steps below to resolve each issue:

Multimedia Audio Controller

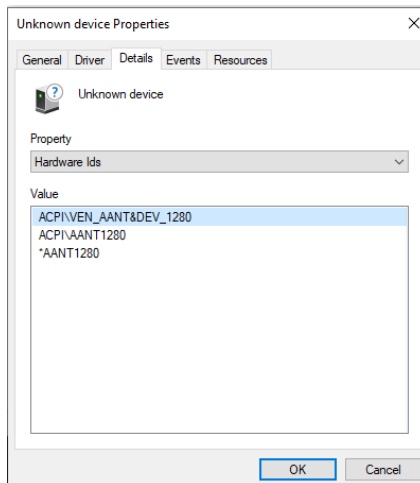
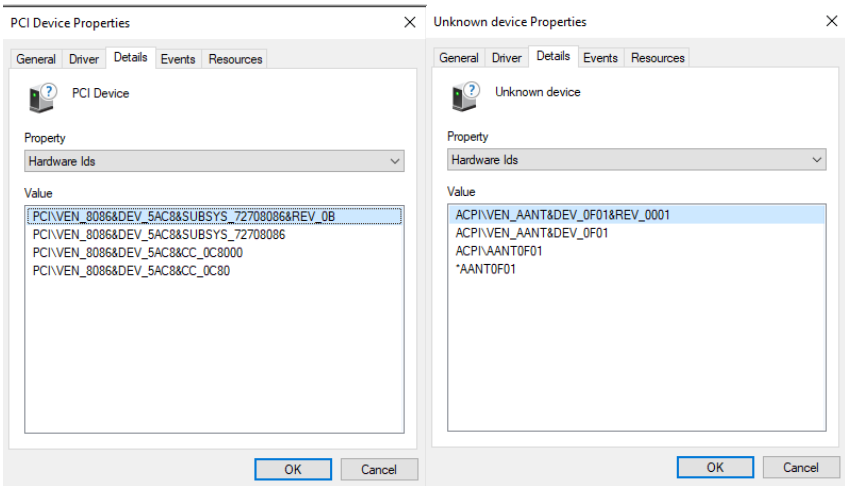


Go into the device BIOS Settings. Navigate the menus as follows:

Chipset -> South Bridge -> HD-Audio Configuration

Find **HD-Audio DSP** and change the setting to "disable."

PCI Device (8086&DEV_5AC8), Unknown Device (AANT0F01), and
VEN_AANT&DEV_1280



Go into the device BIOS Settings. Navigate to the **Boot** menu. Change **OS Selection** to “Windows.”

PCI Device: The unknown PCI device is the PWM signal. It is provided directly from the Apollo Lake chipset, but Intel has not released a Windows driver for this device. This PCI device is not available for Windows 10, it is only supported by Linux.

VEN_AANT&DEV_1280: This is the ADC for Linux, there is no Windows driver. This can be ignored. (Note: error only occurs with Atom E3950 processor SoC)

AANT0F04: This is the FPGA device for Linux.

USB OTG (Linux Only)

This refers to the USB OTG functionality on the USB Type-C port. There is no driver available for Windows 10. The function is only available on Linux.

- Go into the device BIOS Settings. Navigate the menus as follows:
Chipset -> South Bridge -> USB Configuration
- Find USB VBUS and change setting to "Off", and change the XDCI Support setting to "PCI Mode".
- When the OTG function is enabled, Windows will have an unknown USB control (VEN_8086&DEV5AAA).

Appendix A

UP Framework SDK Installation

A.1 Introduction

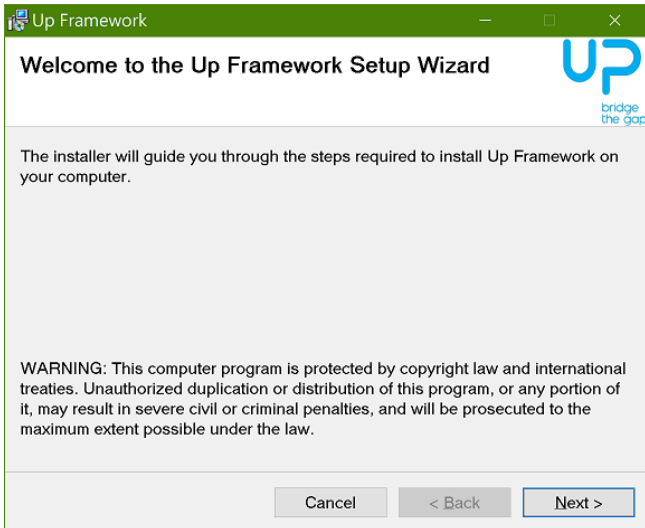
This section provides instructions for the installation of the UP Framework SDK. Instructions are provided for Windows 10 and Windows IoT Core. You can download the latest version of UP Framework SDK from the UP community:

<https://downloads.up-community.org/download/up-sdk-for-windows-10-and-windows-iot/>

A.2 Installation for Windows 10

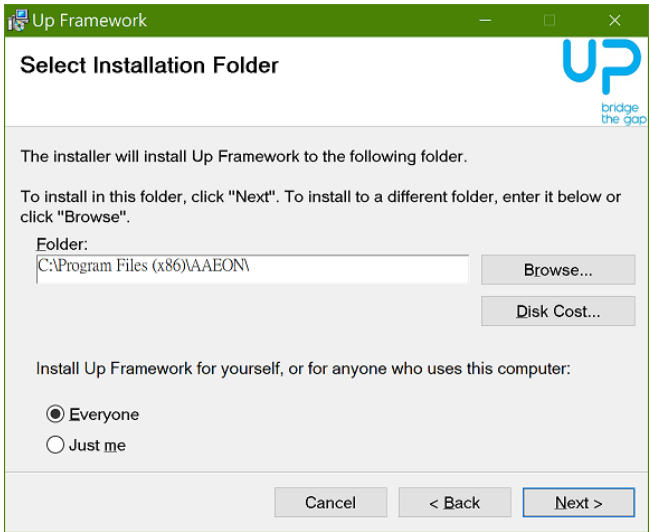
Step 1

Locate the downloaded file UpFrameworkSetup.msi and run the installer. Press “Next” to begin the setup process.



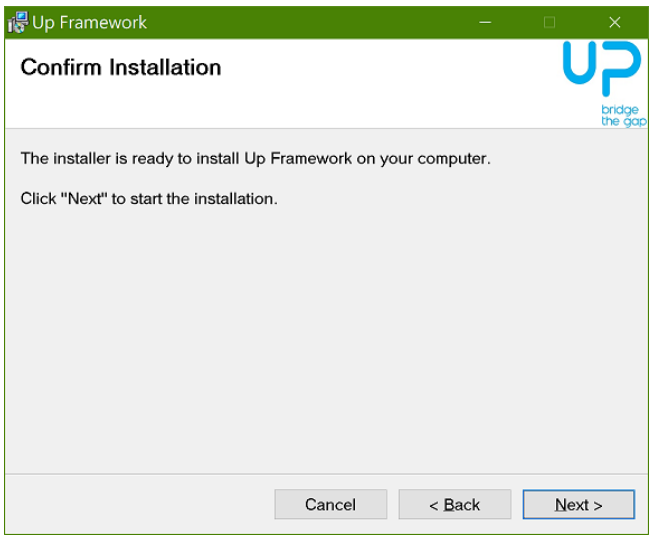
Step 2

Select the installation folder. Default destination path is C:\Program Files(x86)\AAEON\
You may also choose to install the UP Framework SDK for all users or only the current user. Press "Next" to continue installation.



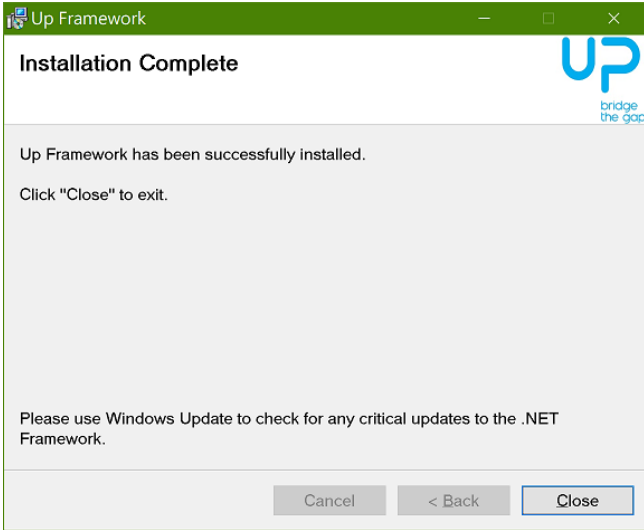
Step 3

Press "Next" to confirm the installation.



Step 4

Press "Close" to exit once setup is complete.



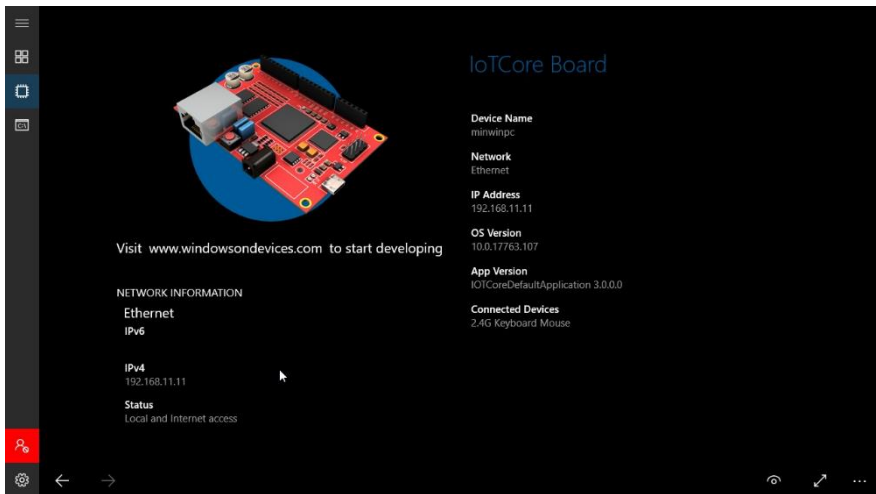
A.3 Installation for Windows IoT Core

Before you begin, make sure you have downloaded and installed the latest version of the Windows IoT Core image from the UP community.

Installation requires using a connected PC with the UP Framework SDK software downloaded and saved. **Note:** Make sure the UP IoT Core device is connected to the same network as the PC you are using to install the software from.

Step 1

Turn on your UP IoT Core device and note the IP address at the home screen.

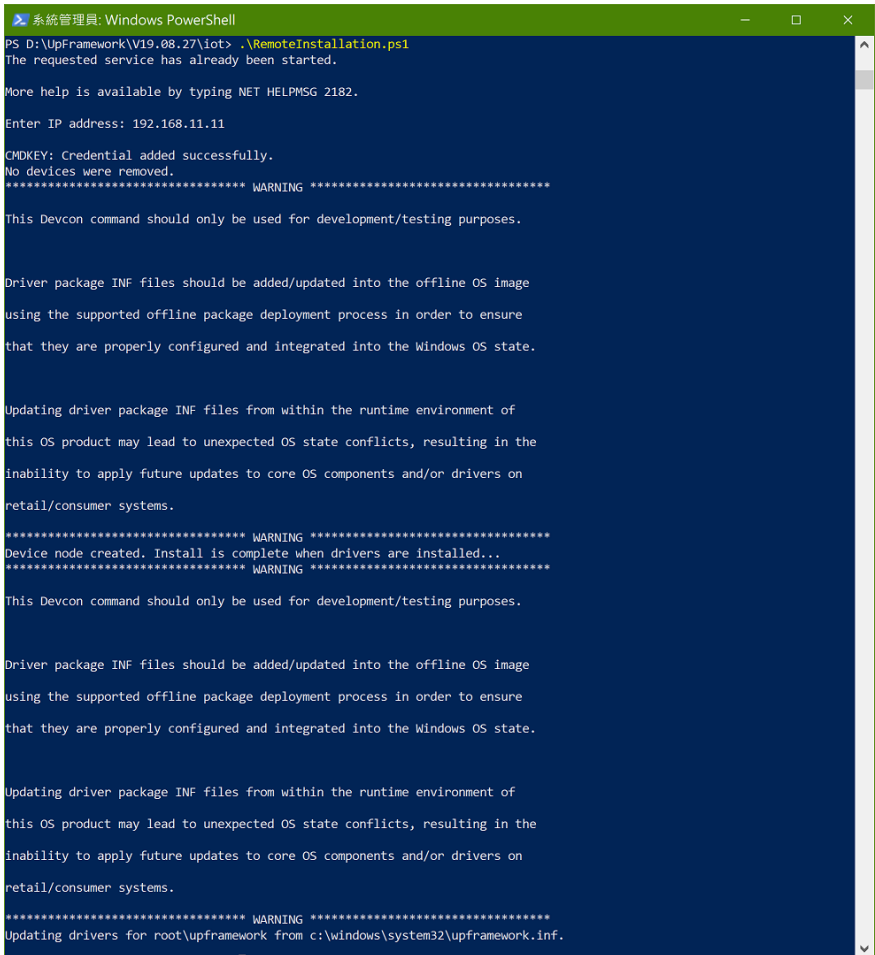


Step 2

Download the UP Framework SDK to your PC and unzip the files.

Open PowerShell as an Administrator. Run the command `RemotelInstallation.ps1` to install the UP Framework SDK.

Enter the IP address of the UP IoT Core device when prompted.



```
系統管理員: Windows PowerShell
PS D:\UpFramework\19.08.27\iot> .\RemotelInstallation.ps1
The requested service has already been started.

More help is available by typing NET HELPMSG 2182.

Enter IP address: 192.168.11.11

CMDKEY: Credential added successfully.
No devices were removed.
***** WARNING *****
This Devcon command should only be used for development/testing purposes.

Driver package INF files should be added/updated into the offline OS image
using the supported offline package deployment process in order to ensure
that they are properly configured and integrated into the Windows OS state.

Updating driver package INF files from within the runtime environment of
this OS product may lead to unexpected OS state conflicts, resulting in the
inability to apply future updates to core OS components and/or drivers on
retail/consumer systems.

***** WARNING *****
Device node created. Install is complete when drivers are installed..
***** WARNING *****
This Devcon command should only be used for development/testing purposes.

Driver package INF files should be added/updated into the offline OS image
using the supported offline package deployment process in order to ensure
that they are properly configured and integrated into the Windows OS state.

Updating driver package INF files from within the runtime environment of
this OS product may lead to unexpected OS state conflicts, resulting in the
inability to apply future updates to core OS components and/or drivers on
retail/consumer systems.

***** WARNING *****
Updating drivers for root\upframework from c:\windows\system32\upframework.inf.
```